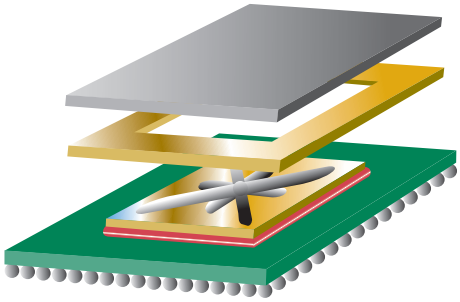
Industrial Products Continued



• Potting and Encapsulants • Thermal Greases • Thermal Management

PRODUCT	DESCRIPTION	VISCOSITY HIGH SHEAR RATE (cP)	CURE SCHEDULE
Potting and Encapsulants			
465-17A/B NEW	Two component, 100% solids, epoxy adhesive with a convenient volumetric mix ratio of 1:1. Developed to connect and encapsulate battery packs used in Electric Vehicles. Excellent adhesion strength to a variety of substrates	12,000	60 min @ 60ºC
505-62	Heat curable epoxy, which forms strong bonds to metals and ceramics. Upon cure has exceptional thermal stability and resistance to water/humidity and solvents	50,000	10 min @ 140ºC
505-88	Black heat curable epoxy (toughened version of 505-62). Strong bonds to metals and ceramics. Exceptional thermal stability and resistance to water/humidity and solvents	45,000	10 min @ 140ºC
629-3A/B NEW	Two component, black, epoxy/acid anhydride encapsulating compound. Excellent adhesion to a variety of substrates with a low coefficient of thermal expansion (α_1 (<T_g) ≈ 23ppm/ºC)	3,000	60 min @ 150ºC
UL94 Rated Potting and Encapsulants			
400-64-1A FR NEW	Two component, flame retardant, thermally conductive epoxy potting/encapsulating compound that can be cured with five different hardeners. Low coefficient of thermal expansion (CTE) and excellent electrical properties. UL94 V0 with 600-09B	Hardener Dependent	Hardener Dependent
505-82A/B	A general two component epoxy systems designed for the encapsulation of electronic assemblies. UL94 V-0 rated	7,500	24 hr @ 25ºC
702-96A/ 600-80B	A general purpose epoxy encapsulating compound with low viscosity upon mixing. UL94 V-0 rated	1,200	24 hr @ 25ºC
2059A/ 600-80B	Flame retardant epoxy-potting compound designed to cure to a glossy white surface. Can be used for potting transformers and power supplies, capacitors and PC board components. UL94 V-0 rated	5,000	24 hr @ 25ºC
Thermal Management (Greases)			
104-25 (Silicone based)	Heat sink compound recommended for high-temperature heat transfer. Offers high thermal conductivity (0.95 W/m•K) and virtually no bleed, separation or evaporation over a wide operation temperature range	Paste	Grease
Thermal Management (Epoxy)			
400-64-1A/ 601-17B	Thermally conductive epoxy potting/encapsulating compound. It features low coefficient of thermal expansion (α_1 (<T_g) ≈ 34ppm/ºC) and excellent electrical properties. Thermal conductivity ~1.25 W/m•K	15,000	24 hr @ 25ºC
504-10-2A/B	Epoxy/acid anhydride compound designed for maximum thermal dissipation at elevated temperature. Develops outstanding electrical properties as well as excellent chemical resistance. Thermal conductivity ~1.94 W/m•K	35,000	Step cure 2 hr @90ºC + 4 hr @180ºC
505-91-1 NEW	Single component, highly filled epoxy encapsulant designed to be cured at temperatures as low as 100ºC within a few hours. Exhibits high thermal conductivity and low coefficient of thermal expansion (α_1 (<T_g) ≈ 29ppm/ºC)	85,000	30 min @ 150ºC
514-105A/B	Epoxy/acid anhydride compound develops excellent adhesion to a variety of substrates and offers low coefficient of thermal expansion (α_1 (<T_g) ≈ 18ppm/ºC). Thermal conductivity ~0.75 W/m•K	30,000	60 min @140ºC
557-90A/ 557-88B NEW	Two component, black, epoxy/acid anhydride encapsulating compound. Excellent adhesion to a variety of substrates with a high thermal conductivity ~0.75 W/m•K. (α_1 (<T_g) ≈ 17ppm/ºC)	36,000	Step cure 60 min @90ºC + 60 min @140ºC